

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10724981
<b>Filing Date:</b>	30-Nov-2003
<b>Title of Invention:</b>	DIE-FIRST MULTI-CHIP MODULES AND METHODS OF MANUFACTURE

<b>First Named Inventor/Applicant Name:</b>	Wendy Lee Wilkins
<b>Filer:</b>	Stephen D. Scanlon/David B. Cochran
<b>Attorney Docket Number:</b>	13312/111

Filed as Small Entity

### Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

Utility Appl issue fee	2501	1	720	720
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1020</b>